

MOSFET – N-Channel, POWERTRENCH®

100 V, 7 A, 23 mΩ

FDS86141

General Description

This N-Channel MOSFET is produced using onsemi's advanced POWERTRENCH process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Features

- Max $R_{DS(on)}$ = 23 mΩ at $V_{GS} = 10$ V, $I_D = 7$ A
- Max $R_{DS(on)}$ = 36 mΩ at $V_{GS} = 6$ V, $I_D = 5.5$ A
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- 100% UIL Tested
- This Device is Pb-Free, Halide Free and is RoHS Compliant

Applications

- DC-DC Conversion

MOSFET MAXIMUM RATINGS

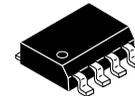
($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V_{DS}	Drain to Source Voltage	100	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current – Continuous – Pulsed	7 30	A
E_{AS}	Single Pulse Avalanche Energy (Note 3)	121	mJ
P_D	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a) $T_A = 25^\circ\text{C}$ (Note 1b)	2.5 1.0	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

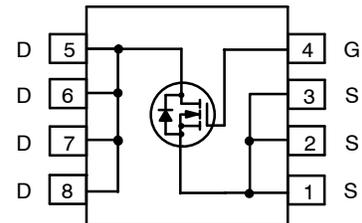
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

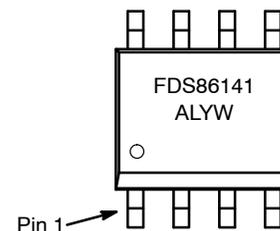
Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	$^\circ\text{C}/\text{W}$



SOIC8
CASE 751EB



MARKING DIAGRAM



FDS86141 = Specific Device Code
A = Assembly Site
L = Wafer Lot Number
YW = Assembly Start Week

ORDERING INFORMATION

Device	Package	Shipping†
FDS86141	SOIC8 (Pb-Free/ Halide Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

FDS86141

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0 V	100	–	–	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25°C	–	67	–	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V	–	–	1	μA
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	–	–	±100	nA

ON CHARACTERISTICS

V _{GS(th)}	Gate to Source Threshold Voltage	V _{GS} = V _{DS} , I _D = 250 μA	2	3.1	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25°C	–	–10	–	mV/°C
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 7 A	–	19	23	mΩ
		V _{GS} = 6 V, I _D = 5.5 A	–	27	37	
		V _{GS} = 10 V, I _D = 7 A, T _J = 125°C	–	33	40	
g _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 7 A	–	19	–	S

DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	–	703	934	pF
C _{oss}	Output Capacitance		–	186	247	
C _{rss}	Reverse Transfer Capacitance		–	8.6	13	
R _G	Gate Resistance		–	0.5	–	Ω

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	V _{DD} = 50 V, I _D = 7 A, V _{GS} = 10 V, R _{GEN} = 6 Ω	–	8.3	17	ns
t _r	Rise Time		–	3.2	10	
t _{d(off)}	Turn-Off Delay Time		–	14.3	26	
t _f	Fall Time		–	3.2	10	
Q _{g(TOT)}	Total Gate Charge	V _{GS} = 0 V to 10 V, V _{DD} = 50 V, I _D = 7 A	–	11.8	16.5	nC
		V _{GS} = 0 V to 5 V, V _{DD} = 50 V, I _D = 7 A	–	6.7	9.4	
Q _{gs}	Gate to Source Charge	V _{DD} = 50 V, I _D = 7 A	–	3.4	–	nC
Q _{gd}	Gate to Drain "Miller" Charge		–	3.1	–	

DRAIN-SOURCE DIODE CHARACTERISTICS

V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 7 A (Note 2)	–	0.8	1.3	V
		V _{GS} = 0 V, I _S = 2 A (Note 2)	–	0.8	1.2	
t _{rr}	Reverse Recovery Time	I _F = 7 A, di/dt = 100 A/μs	–	43	69	ns
Q _{rr}	Reverse Recovery Charge		–	39	62	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

- R_{θJA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.



a) 50°C/W when mounted on a 1 in² pad of 2 oz. copper.



b) 125°C/W when mounted on a minimum pad.

- Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%
- Starting T_J = 25°C; N-ch: L = 3 mH, I_{AS} = 9 A, V_{DD} = 100 V, V_{GS} = 10 V

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

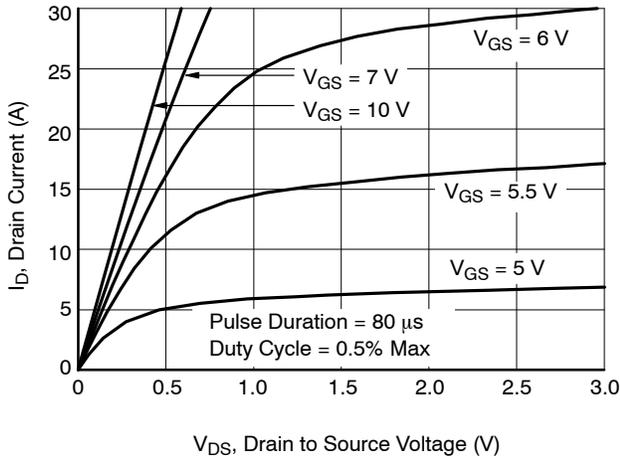


Figure 1. On Region Characteristics

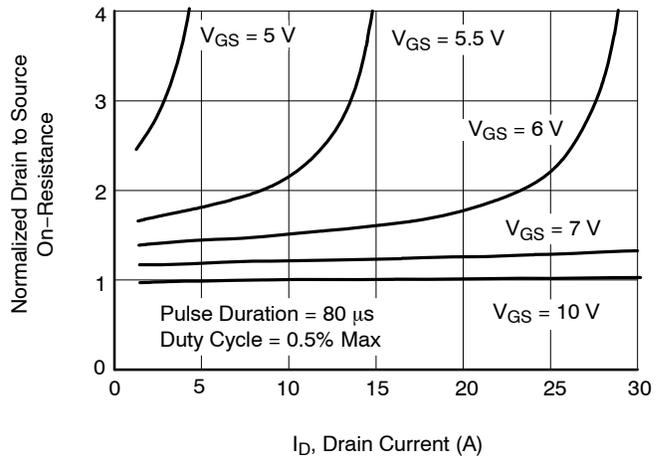


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

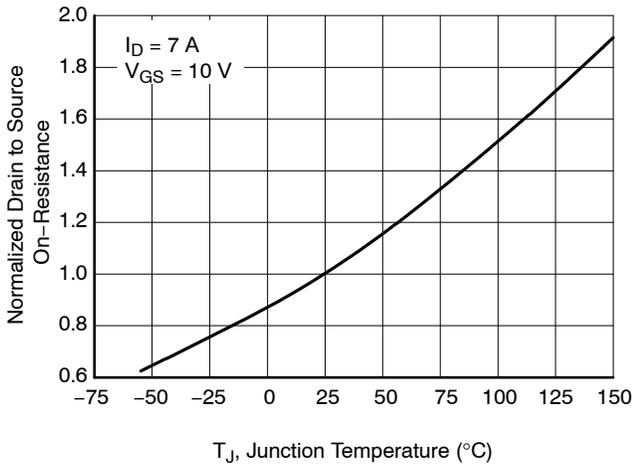


Figure 3. Normalized On Resistance vs. Junction Temperature

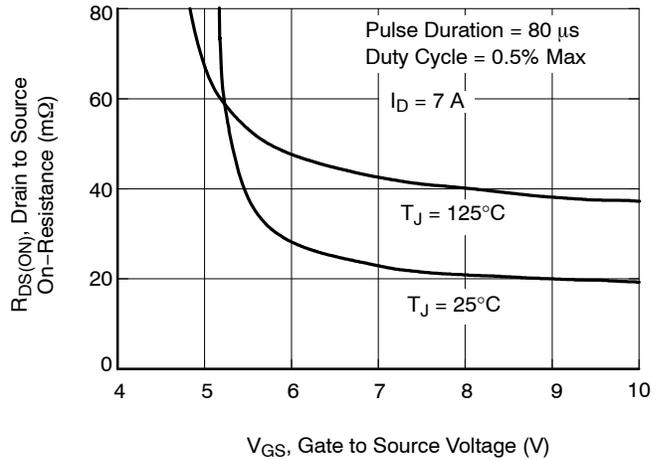


Figure 4. On-Resistance vs. Gate to Source Voltage

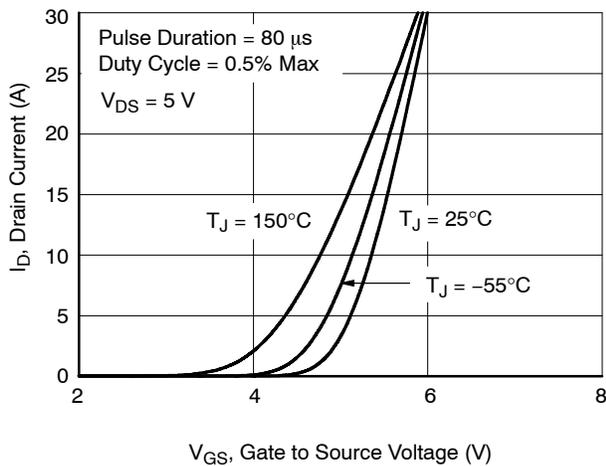


Figure 5. Transfer Characteristics

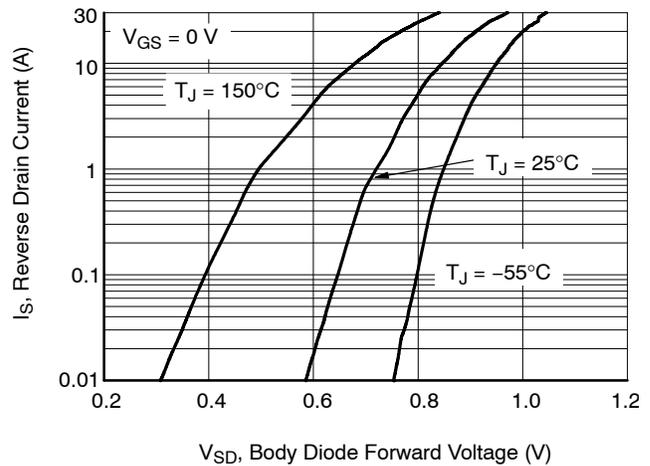


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

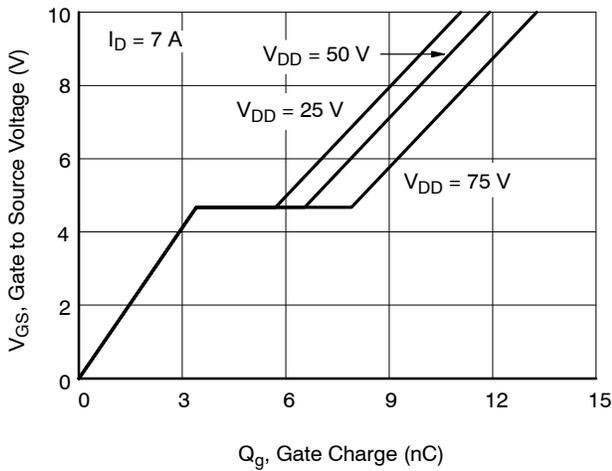


Figure 7. Gate Charge Characteristics

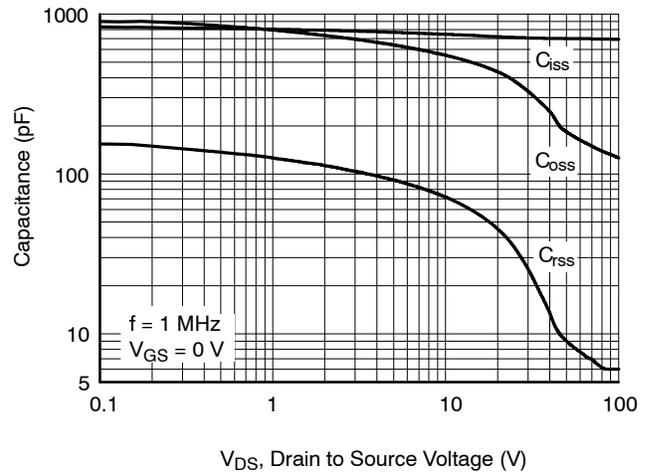


Figure 8. Capacitance vs. Drain to Source Voltage

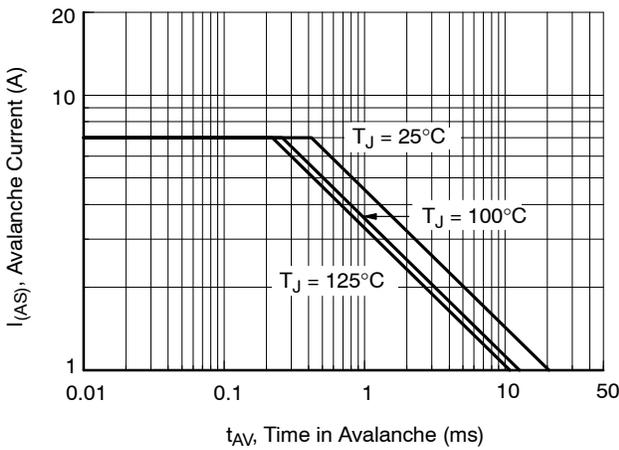


Figure 9. Unclamped Inductive Switching Capability

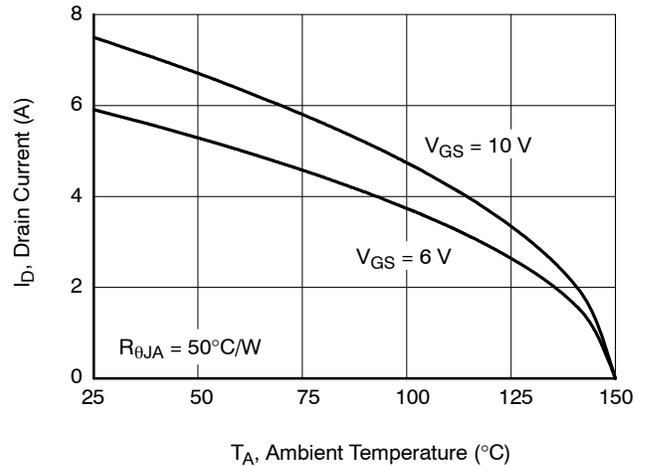


Figure 10. Maximum Continuous Drain Current vs. Ambient Temperature

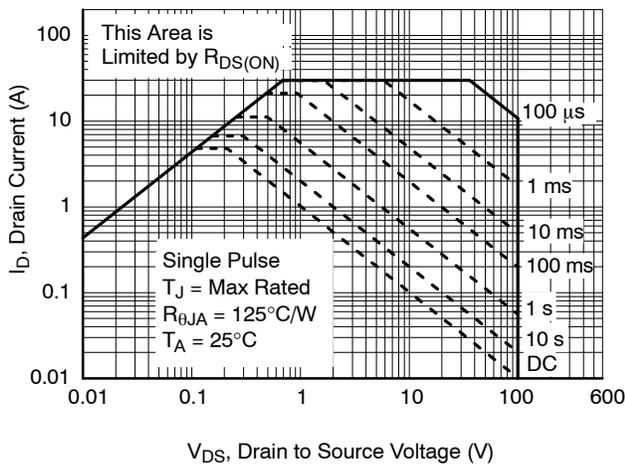


Figure 11. Forward Bias Safe Operating Area

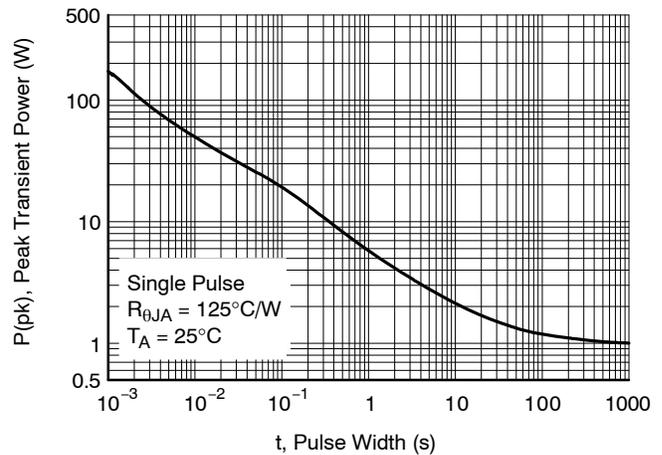


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

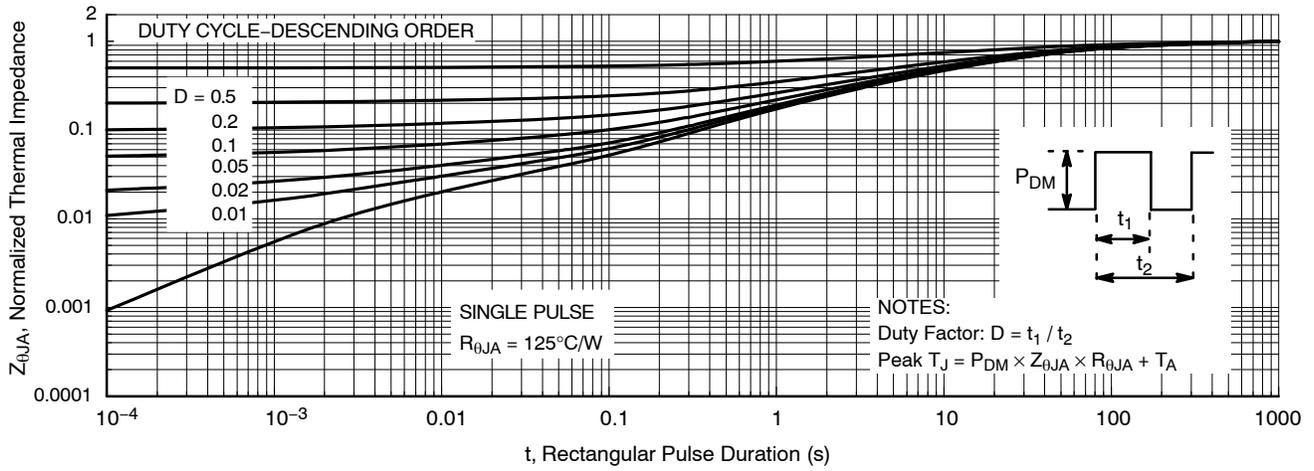
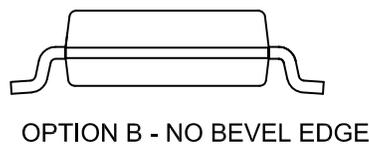
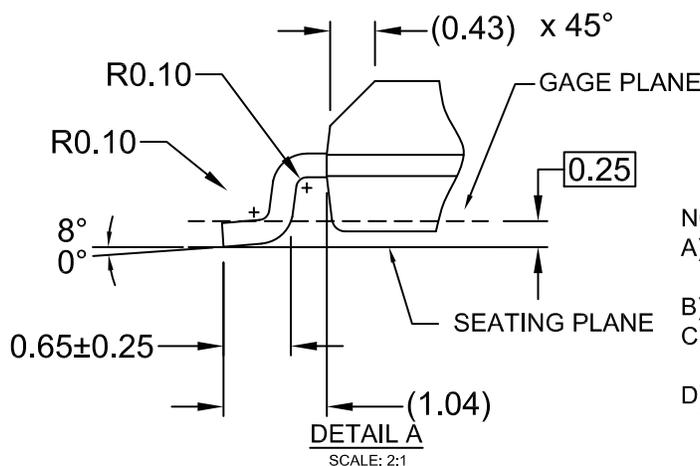
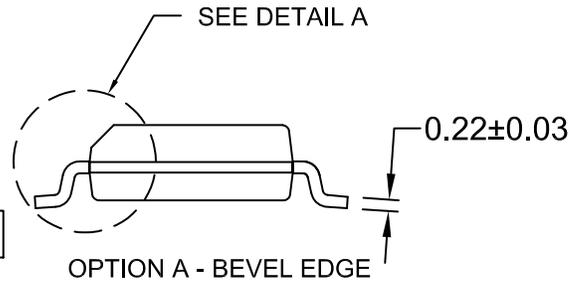
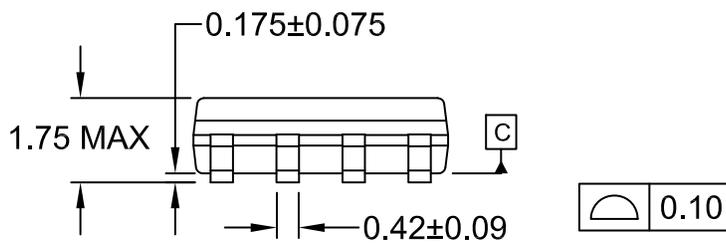
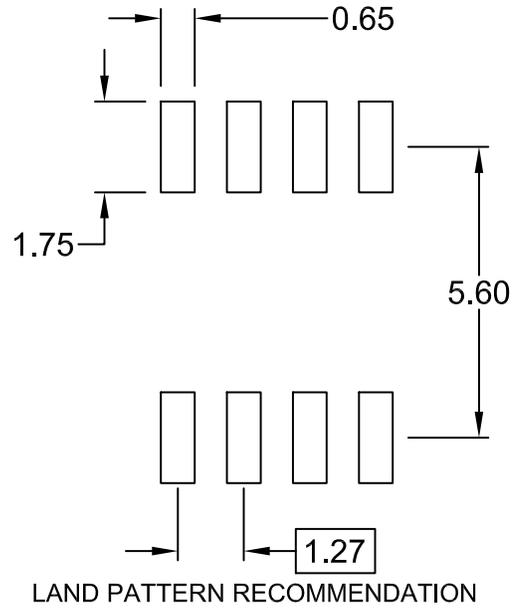
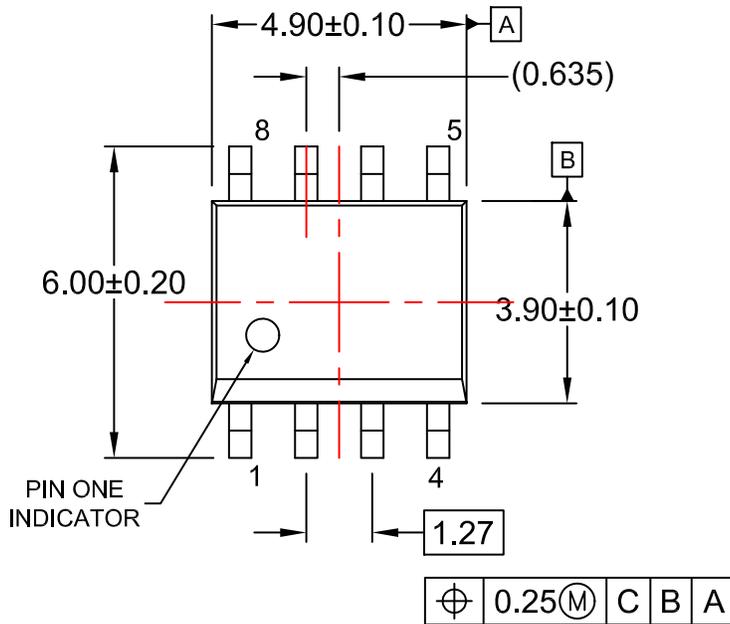


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

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CASE 751EB
ISSUE A

DATE 24 AUG 2017



- NOTES:
 A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
 D) LANDPATTERN STANDARD: SOIC127P600X175-8M

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